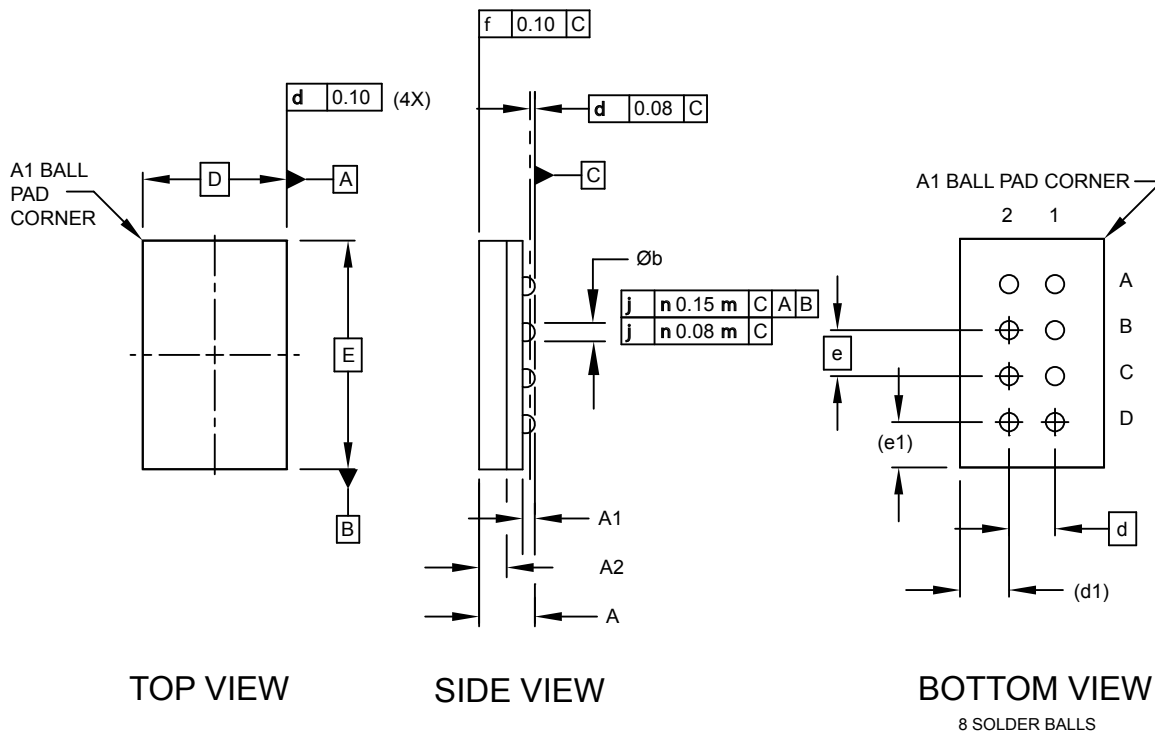




COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.81	0.91	1.00	
A1	0.15	0.20	0.25	
A2	0.40	0.45	0.50	
b	0.25	0.30	0.35	
D	2.35 BSC			
E	3.73 BSC			
e	0.75 BSC			
e1	0.74 REF			
d	0.75 BSC			
d1	0.80 REF			

Notes:

1. This drawing is for general
2. Dimension 'b' is measured at the maximum solder ball diameter.
3. Solder ball composition shall be 95.5Sn-4.0Ag-.5Cu.

6/11/13

TITLE
8U2-1, 8-ball, 2.35 x 3.73 mm Body, 0.75 mm pitch,
Very Thin, Fine-Pitch Ball Grid Array Package
(VFBGA)

GPC
GWW

DRAWING NO.
8U2-1

REV.
G